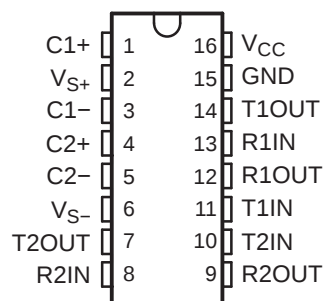


DUAL RS-232 DRIVER/RECEIVER WITH IEC61000-4-2 PROTECTION

FEATURES

- Meets or Exceeds TIA/RS-232-F and ITU Recommendation V.28
- Operates From a Single 5-V Power Supply With 1.0- μ F Charge-Pump Capacitors
- Operates up to 120 kbit/s
- Two Drivers and Two Receivers
- ± 30 -V Input Levels
- Low Supply Current . . . 8 mA Typical
- ESD Protection Exceeds JESD22
 - 2000-V Human-Body Model (HBM) (A114-A)
- Upgrade With Improved ESD (15-kV HBM) and 0.1- μ F Charge-Pump Capacitors Is Available With the TRS202

D, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



APPLICATIONS

- TIA/RS-232-F
- Battery-Powered Systems
- Terminals
- Modems
- Computers

DESCRIPTION/ORDERING INFORMATION

The TRS232 is a dual driver/receiver that includes a capacitive voltage generator to supply TIA/RS-232-F voltage levels from a single 5-V supply. Each receiver converts TIA/RS-232-F inputs to 5-V TTL/CMOS levels. This receiver has a typical threshold of 1.3 V, a typical hysteresis of 0.5 V, and can accept ± 30 -V inputs. Each driver converts TTL/CMOS input levels into TIA/RS-232-F levels. The driver, receiver, and voltage-generator functions are available as cells in the Texas Instruments LinASIC™ library.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾ (²)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube of 25	TRS232CN	TRS232CN
	SOIC – D	Tube of 40	TRS232CD	TRS232C
		Reel of 2500	TRS232CDR	
	SOIC – DW	Tube of 40	TRS232CDW	TRS232C
		Reel of 2000	TRS232CDWR	
	SOP – NS	Reel of 2000	TRS232CNSR	TRS232C
	TSSOP – PW	Tube of 25	TRS232CPW	TRS232C
		Reel of 2000	TRS232CPWR	
–40°C to 85°C	PDIP – N	Tube of 25	TRS232IN	TRS232IN
	SOIC – D	Tube of 40	TRS232ID	TRS232I
		Reel of 2500	TRS232IDR	
	SOIC – DW	Tube of 40	TRS232IDW	TRS232I
		Reel of 2000	TRS232IDWR	
	SOP – NS	Reel of 2000	TRS232INSR	TRS232I
	TSSOP – PW	Tube of 25	TRS232IPW	TRS232I
		Reel of 2000	TRS232IPWR	

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

FUNCTION TABLES

Each Driver⁽¹⁾

INPUT TnIN	OUTPUT TnOUT
L	H
H	L

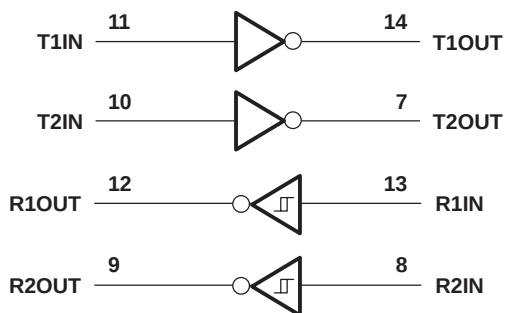
(1) H = high level, L = low level

Each Receiver⁽¹⁾

INPUT RnIN	OUTPUT RnOUT
L	H
H	L

(1) H = high level, L = low level

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Input supply voltage range ⁽²⁾		–0.3	6	V
V _{S+}	Positive-output supply voltage range		V _{CC} – 0.3	15	V
V _{S–}	Negative-output supply voltage range		–0.3	–15	V
V _I	Input voltage range	Driver	–0.3	V _{CC} + 0.3	V
		Receiver		±30	
V _O	Output voltage range	T1OUT, T2OUT	V _{S–} – 0.3	V _{S+} + 0.3	V
		R1OUT, R2OUT	–0.3	V _{CC} + 0.3	
	Short-circuit duration	T1OUT, T2OUT		Unlimited	
θ _{JA}	Package thermal impedance ⁽³⁾⁽⁴⁾	D package		73	°C/W
		DW package		57	
		N package		67	
		NS package		64	
		PW package		108	
T _J	Operating virtual junction temperature			150	°C
T _{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.
- (3) Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) – T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5	5	5.5	V
V _{IH}	High-level input voltage	T1IN, T2IN	2			V
V _{IL}	Low-level input voltage	T1IN, T2IN			0.8	V
	Receiver input voltage	R1IN, R2IN			±30	V
T _A	Operating free-air temperature	TRS232C	0		70	°C
		TRS232I	–40		85	

Electrical Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
I _{CC} Supply current	V _{CC} = 5.5 V, All outputs open, T _A = 25°C		8	10	mA

- (1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.
- (2) All typical values are at V_{CC} = 5 V and T_A = 25°C.

DRIVER SECTION

Electrical Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature range

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}	High-level output voltage	T1OUT, T2OUT R _L = 3 kΩ to GND	5	7		V
V _{OL}	Low-level output voltage ⁽³⁾	T1OUT, T2OUT R _L = 3 kΩ to GND		–7	–5	V
r _o	Output resistance	T1OUT, T2OUT V _{S+} = V _{S–} = 0, V _O = ±2 V	300			Ω
I _{OS} ⁽⁴⁾	Short-circuit output current	T1OUT, T2OUT V _{CC} = 5.5 V, V _O = 0		±10		mA
I _{IS}	Short-circuit input current	T1IN, T2IN V _I = 0			200	μA

(1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

(2) All typical values are at V_{CC} = 5 V and T_A = 25°C.

(3) The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.

(4) Not more than one output should be shorted at a time.

Switching Characteristics⁽¹⁾

V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Driver slew rate	R _L = 3 kΩ to 7 kΩ, See Figure 2			30	V/μs
SR(t)	Driver transition region slew rate	See Figure 3		3		V/μs
	Data rate	One TnOUT switching		120		kbit/s

(1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

RECEIVER SECTION

Electrical Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature range

PARAMETER			TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}	High-level output voltage	R1OUT, R2OUT	I _{OH} = –1 mA	3.5			V
V _{OL}	Low-level output voltage ⁽³⁾	R1OUT, R2OUT	I _{OL} = 3.2 mA			0.4	V
V _{IT+}	Receiver positive-going input threshold voltage	R1IN, R2IN	V _{CC} = 5 V, T _A = 25°C		1.7	2.4	V
V _{IT–}	Receiver negative-going input threshold voltage	R1IN, R2IN	V _{CC} = 5 V, T _A = 25°C	0.8	1.2		V
V _{hys}	Input hysteresis voltage	R1IN, R2IN	V _{CC} = 5 V	0.2	0.5	1	V
r _i	Receiver input resistance	R1IN, R2IN	V _{CC} = 5 V, T _A = 25°C	3	5	7	kΩ

(1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

(2) All typical values are at V_{CC} = 5 V and T_A = 25°C.

(3) The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.

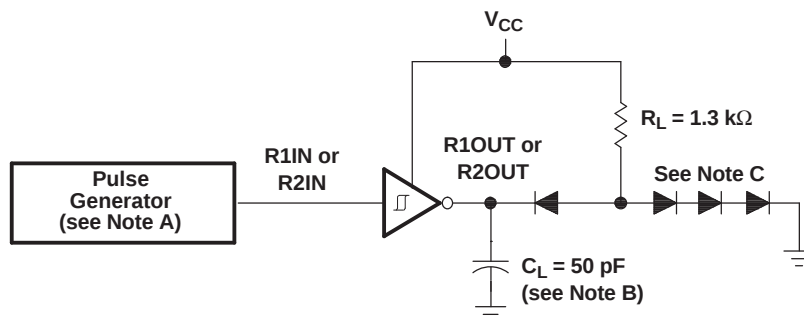
Switching Characteristics⁽¹⁾

V_{CC} = 5 V, T_A = 25°C (see [Figure 1](#))

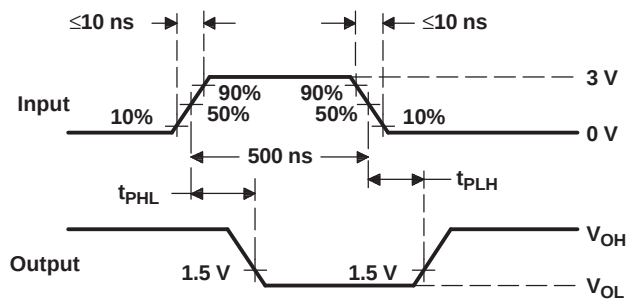
PARAMETER		TYP	UNIT
t _{PLH(R)}	Receiver propagation delay time, low- to high-level output	500	ns
t _{PHL(R)}	Receiver propagation delay time, high- to low-level output	500	ns

(1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

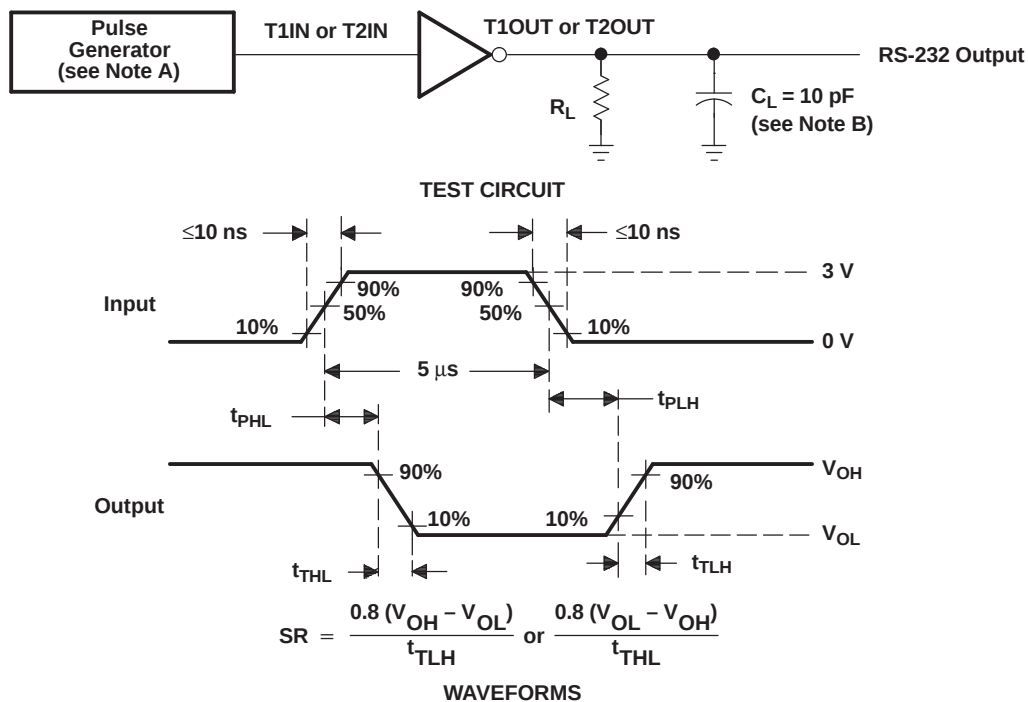


WAVEFORMS

- A. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, duty cycle $\leq 50\%$.
- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N3064 or equivalent.

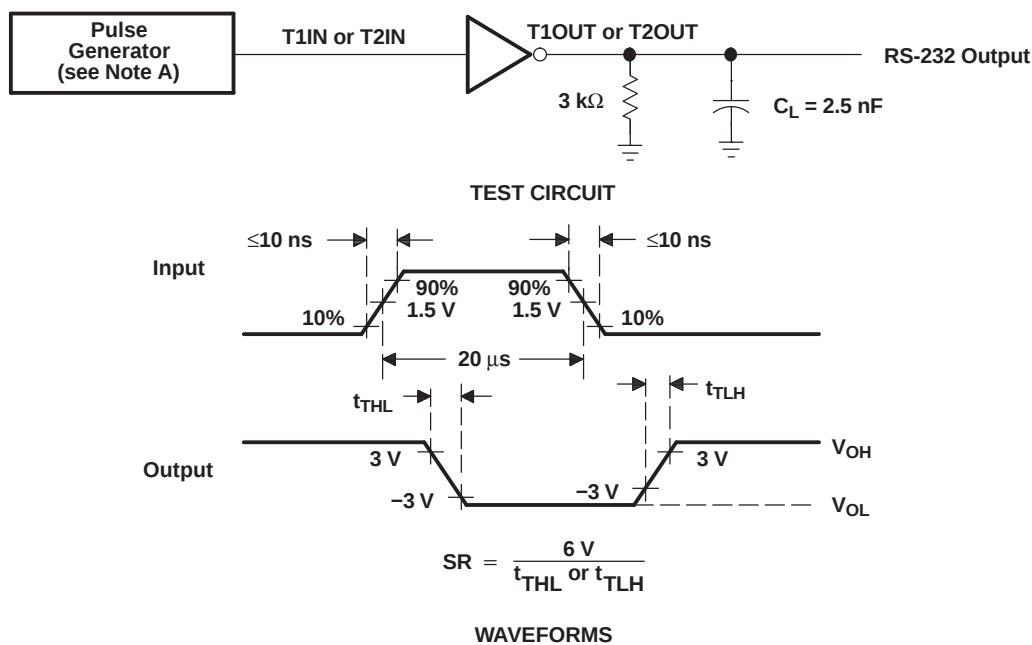
Figure 1. Receiver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements

PARAMETER MEASUREMENT INFORMATION (continued)



- A. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, duty cycle $\leq 50\%$.
- B. C_L includes probe and jig capacitance.

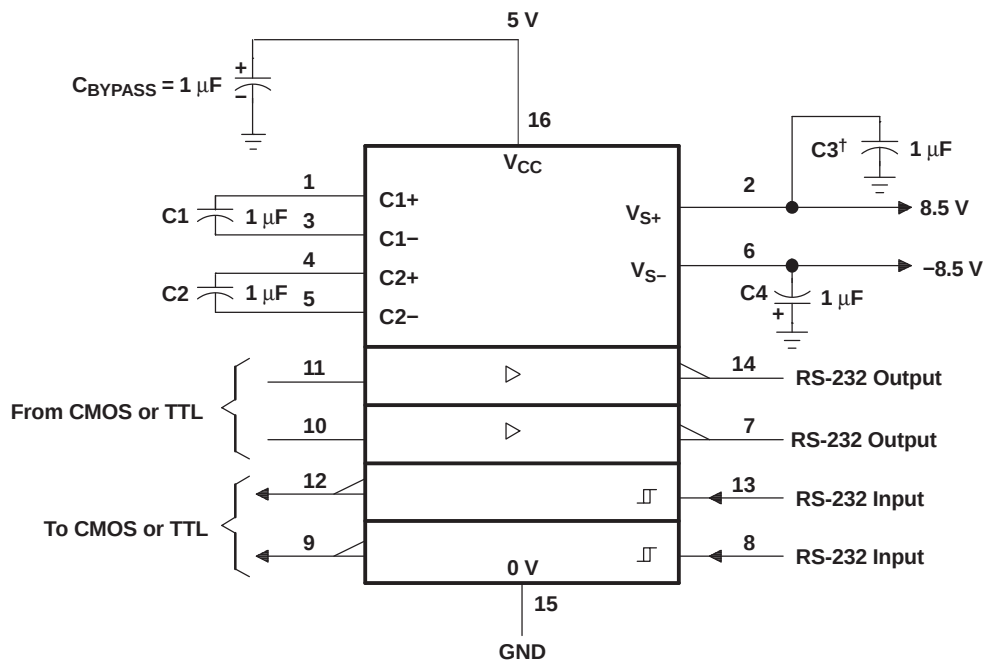
Figure 2. Driver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements (5- μs Input)



- A. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, duty cycle $\leq 50\%$.

Figure 3. Test Circuit and Waveforms for t_{THL} and t_{TLH} Measurements (20- μs Input)

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

- A. Resistor values shown are nominal.
- B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown. In addition to the 1- μ F capacitors shown, the TRS202 can operate with 0.1- μ F capacitors.

Figure 4. Typical Operating Circuit

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TRS232D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS232	Samples
TRS232DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS232	Samples
TRS232DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS232	Samples
TRS232DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS232	Samples
TRS232ID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS232I	Samples
TRS232IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TRS232IN	Samples
TRS232INE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TRS232IN	Samples
TRS232N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TRS232N	Samples
TRS232NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS232	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- ⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- ⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- ⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- ⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS232DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TRS232DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TRS232DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TRS232NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



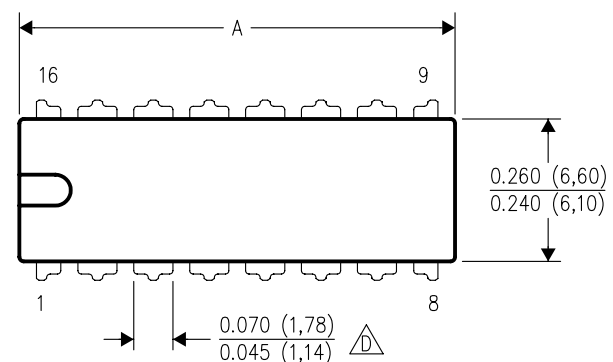
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS232DR	SOIC	D	16	2500	333.2	345.9	28.6
TRS232DR	SOIC	D	16	2500	367.0	367.0	38.0
TRS232DWR	SOIC	DW	16	2000	367.0	367.0	38.0
TRS232NSR	SO	NS	16	2000	367.0	367.0	38.0

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

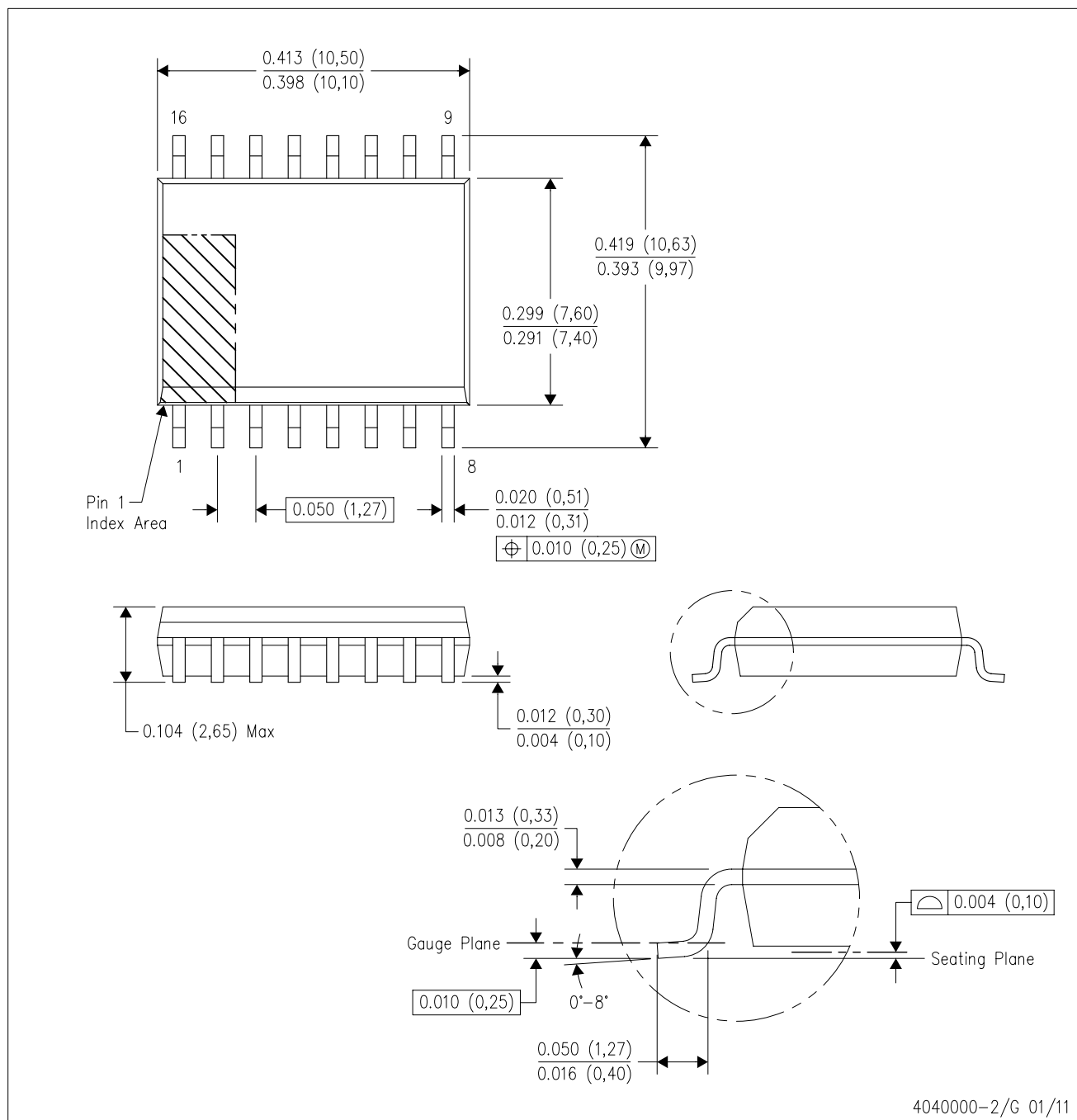
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AA.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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